

6.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@T_A = +25°C)

| V _{RRM} (V) | I _O (A) | V _F (V) | I _R (μA) |
|----------------------|--------------------|--------------------|---------------------|
| 1000 | 6.0 | 0.96 | 5 |

Description and Applications

General purpose use in AC-to-DC bridge full wave rectification for Fast Charging, Switching Power Supply, USB PD, Adapter and 3-in-1 DTV Power Board, etc.

Features and Benefits

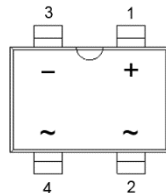
- Glass Passivated Die Construction
- Miniature Surface Mount Package Saves Space on PC Boards
- High Current Capability
- High Forward Current Capability up to 6.0A
- High Heat Dissipation Capability
- Low Profile Package
- Low Forward Voltage Drop
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

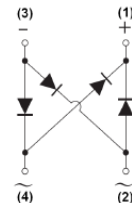
- Case: HBS
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: As Marked on Body
- Weight: 0.387grams (Approximate)



Top View



Pin Diagram



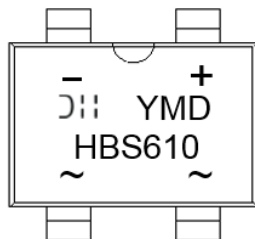
Internal Schematic

Ordering Information (Note 4)

| Part Number | Compliance | Case | Packaging |
|-------------|------------|------|-------------------|
| HBS610-13 | Commercial | HBS | 2,500/Tape & Reel |

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



HBS610 = Product Type Marking Code
 YMD = Date Code Marking
 Y = Last Digit of Year (ex: 0 = 2020)
 M = See Month/Code Table Below
 D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|--|--|-------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 1,000 | V |
| RMS Reverse Voltage | V _{R(RMS)} | 700 | V |
| Average Rectified Output Current (Note 5) @ T _A = +25°C | I _O | 6.0 | A |
| Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 170 | A |
| Non-Repetitive Peak Forward Surge Current, 1.0ms Single Half Sine-Wave Superimposed on Rated Load | I _{FSM} | 280 | A |
| I ² t Rating for Fusing (1ms < t < 8.3ms) | I ² t | 120 | A ² S |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element) | R _{θJA} | 75 | °C/W |
| Typical Thermal Resistance, Junction to Lead (Per Element) | R _{θJL} | 14 | °C/W |
| Typical Thermal Resistance, Junction to Case (Per Element) | R _{θJC} | 10 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|--------------------|-------|----------------------|----------------------|------|---|
| Reverse Breakdown Voltage (Note 6) | V _{(BR)R} | 1,000 | — | — | V | I _R = 10μA |
| Forward Voltage (Per Element) | V _F | — | 0.83 0.88 0.91 | 0.88 0.93 0.96 | V | I _F = 1A, T _A = +25°C I _F = 3A, T _A = +25°C I _F = 6A, T _A = +25°C |
| Leakage Current (Note 6) (Per Element) | I _R | — | 0.15 20 | 5 100 | μA | V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C |
| Total Capacitance (Per Element) | C _T | — | 50 | — | pF | V _R = 4V, f = 1.0MHz |

Notes: 5. Device mounted on 15mmx12mmx1.6mm AL Pad attached on 100mmx75mmx27mm Fin heatsink. Thermal resistance test performed in accordance with JESD-51.
6. Short duration pulse test used to minimize self-heating effect.

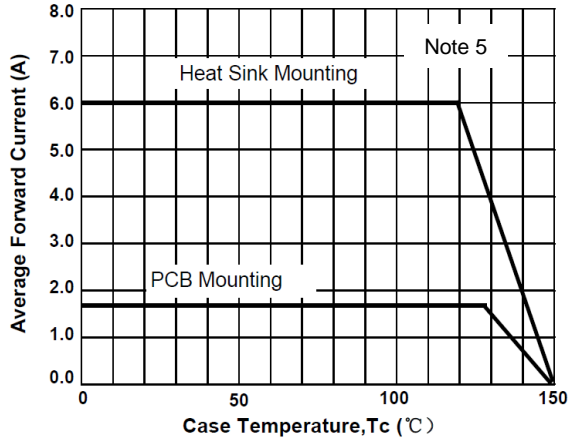


Figure 1. Forward Current Derating

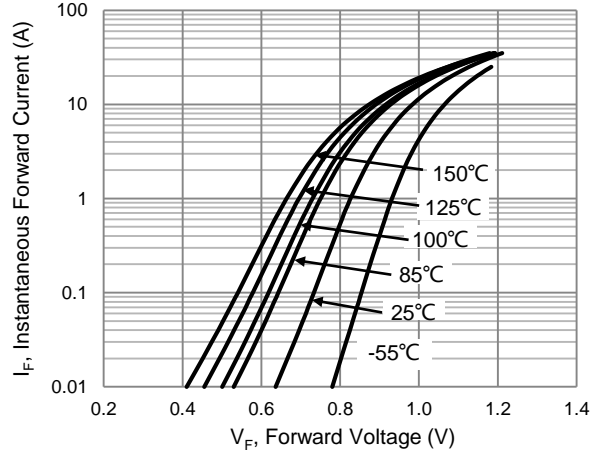


Figure 2. Typical Forward Characteristics

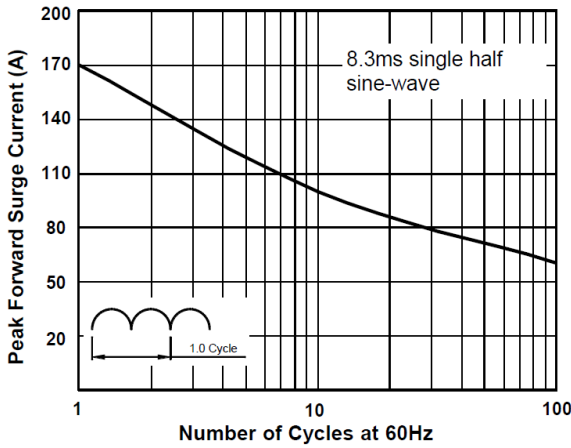


Figure 3. Maximum Non-Repetitive Forward Surge Current

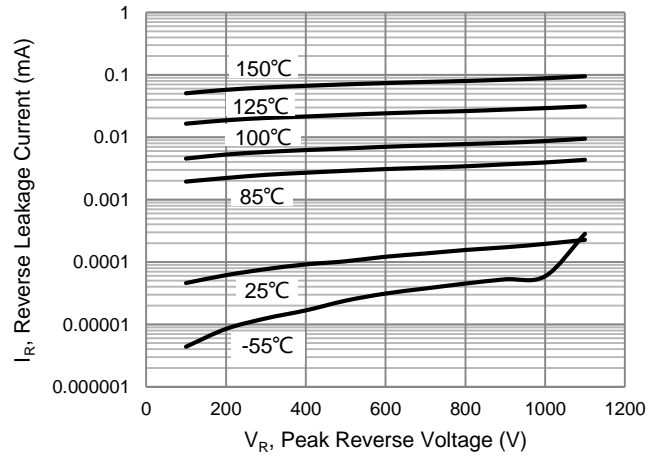


Figure 4. Typical Reverse Characteristics

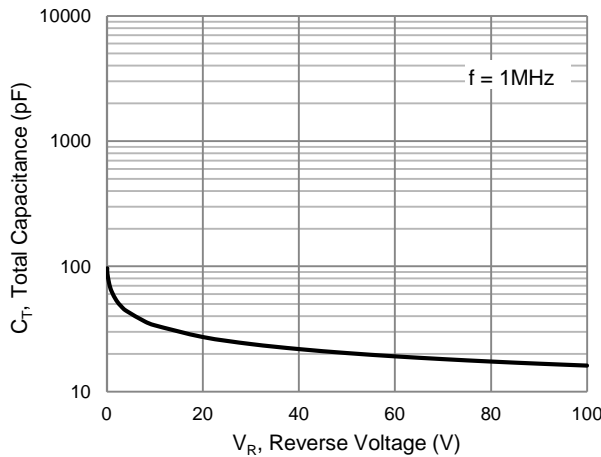
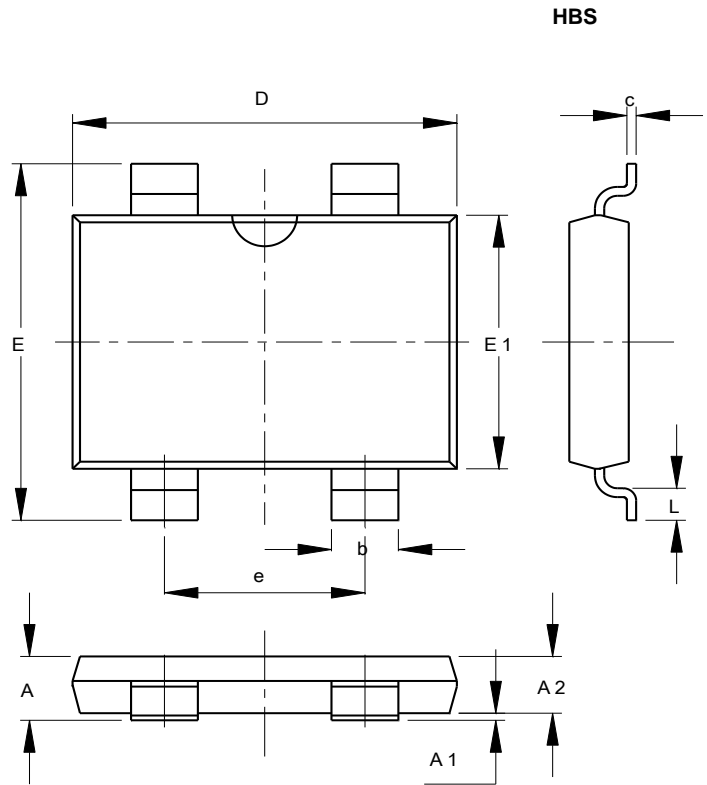


Figure 5. Typical Total Capacitance

Package Outline Dimensions

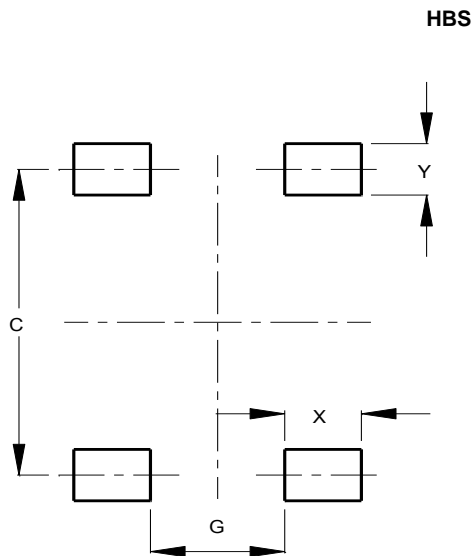
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



| HBS | | | |
|-----------------------------|-------|-------|-----|
| Dim | Min | Max | Typ |
| A | 1.45 | 1.80 | -- |
| A1 | 0.00 | 0.20 | -- |
| A2 | 1.45 | 1.65 | -- |
| b | 1.70 | 1.90 | -- |
| c | 0.15 | 0.35 | -- |
| D | 10.05 | 10.35 | -- |
| E | 9.75 | 10.05 | -- |
| E1 | 6.85 | 7.15 | -- |
| e | 5.25 | 5.60 | -- |
| L | 0.45 | 0.95 | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 8.92 |
| G | 3.50 |
| X | 2.00 |
| Y | 1.50 |

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